

L Number	Hits	Search Text	DB	Time stamp
-	53	h011021/\$.ipc. and (substrate or wafer or susceptor) and pin and (resilien\$2 or spring or flexib5) and heat\$3	USPAT; US-PGPUB	2002/07/22 07:56
-	0	(h011021/\$.ipc. and (substrate or wafer or susceptor) and pin and (resilien\$2 or spring or flexib5) and heat\$3) and @ad<19971119	USPAT; US-PGPUB	2002/07/22 07:57
-	0	(h011021/\$.ipc. and (substrate or wafer or susceptor) and pin and (resilien\$2 or spring or flexib5) and heat\$3) and @ad<19971119	USPAT; US-PGPUB	2002/07/22 07:57
-	22	h011021/\$.ipc. and (substrate or wafer or susceptor) and pin and (resilien\$2 or spring or flexib5) and heat\$3	JPO; DERWENT	2002/07/22 08:58
-	24	h011021/\$.ipc. and (substrate or wafer or susceptor or work) and pin and (resilien\$2 or spring or flexib5) and heat\$3	JPO; DERWENT	2002/07/22 09:01
-	2	(h011021/\$.ipc. and (substrate or wafer or susceptor or work) and pin and (resilien\$2 or spring or flexib5) and heat\$3) not (h011021/\$.ipc. and (substrate or wafer or susceptor) and pin and (resilien\$2 or spring or flexib5) and heat\$3)	JPO; DERWENT	2002/07/22 08:59
-	315	h011021/\$.ipc. and (substrate or wafer or susceptor or work) and pin and (resilien\$2 or spring or flexib5)	JPO; DERWENT	2002/07/22 09:46
-	2	(h011021/\$.ipc. and (substrate or wafer or susceptor or work) and pin and (resilien\$2 or spring or flexib5)) and quartz and heat\$3	JPO; DERWENT	2002/07/22 09:44
-	1	c23c016/\$.ipc. and (substrate or wafer or susceptor or work) and pin and (resilien\$2 or spring or flexib5)and heat	JPO; DERWENT	2002/07/22 10:09
-	14	c23c016/\$.ipc. and (substrate or wafer or susceptor or work) and pin and (resilien\$2 or spring or flexib5)	JPO; DERWENT	2002/07/22 10:00
-	2	c23c016/\$.ipc. and (substrate or wafer or susceptor or work) and pin and (resilien\$2 or spring or flexib5)and heat\$3	JPO; DERWENT	2002/07/22 10:10
-	0	(156/345.51-345.55).ccls. and (substrate or wafer or susceptor or work) and pin and (resilien\$2 or spring or flexib5) and heat\$3	JPO; DERWENT	2002/07/22 10:11
-	0	(156/345.51-345.55).ccls.	JPO; DERWENT	2002/07/22 10:11
-	44	(156/345.51-345.55).ccls. and (substrate or wafer or susceptor or work) and pin and (resilien\$2 or spring or flexib5) and heat\$3	USPAT; US-PGPUB	2002/07/22 10:15
-	44	(156/345.51-345.55).ccls. and (substrate or wafer or susceptor or work or pedestal) and pin and (resilien\$2 or spring or flexib5) and heat\$3	USPAT; US-PGPUB	2002/07/22 11:03
-	17	((156/345.51-345.55).ccls. and (substrate or wafer or susceptor or work or pedestal) and pin and (resilien\$2 or spring or flexib5) and heat\$3) and quartz	USPAT; US-PGPUB	2002/07/22 12:34
-	17	leaf adj spring with quartz	USPAT; US-PGPUB	2002/07/22 12:47
-	343	((118/722-730).ccls. and pin and (resilien\$2 or spring or flexib5)	USPAT; US-PGPUB	2002/07/22 12:49
-	246	((118/722-730).ccls. and pin and (resilien\$2 or spring or flexib5)) and @ad<19971119	USPAT; US-PGPUB	2002/07/22 12:52
-	120	((118/722-730).ccls. and pin and (resilien\$2 or spring or flexib5)) and @ad<19971119) and clamp\$4	USPAT; US-PGPUB	2002/07/22 14:28
-	1	4836905.pn.	USPAT; US-PGPUB	2002/07/22 14:29